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2SB1321A

Silicon PNP epitaxial planar type

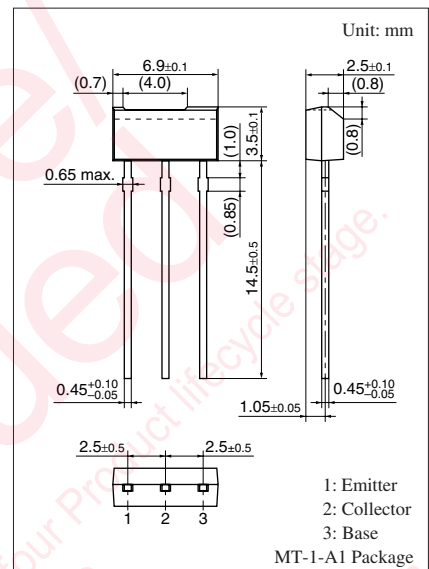
For low-frequency output amplification and driver amplification
Complementary to 2SD1992A

■ Features

- Allowing supply with the radial taping
- Large collector power dissipation P_C (600 mW)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-60	V
Collector-emitter voltage (Base open)	V_{CEO}	-50	V
Emitter-base voltage (Collector open)	V_{EBO}	-7	V
Collector current	I_C	-0.5	A
Peak collector current	I_{CP}	-1	A
Collector power dissipation	P_C	600	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10 \mu\text{A}$, $I_E = 0$	-60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2 \text{ mA}$, $I_B = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu\text{A}$, $I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20 \text{ V}$, $I_E = 0$			-0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -20 \text{ V}$, $I_B = 0$			-1	μA
Forward current transfer ratio	h_{FE1}^{*2}	$V_{CE} = -10 \text{ V}$, $I_C = -10 \text{ mA}$	85		340	—
	h_{FE2}^{*1}	$V_{CE} = -10 \text{ V}$, $I_C = -500 \text{ mA}$	40			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -300 \text{ mA}$, $I_B = -30 \text{ mA}$		-0.35	-0.60	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}$, $I_E = 10 \text{ mA}$, $f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$		6	15	pF

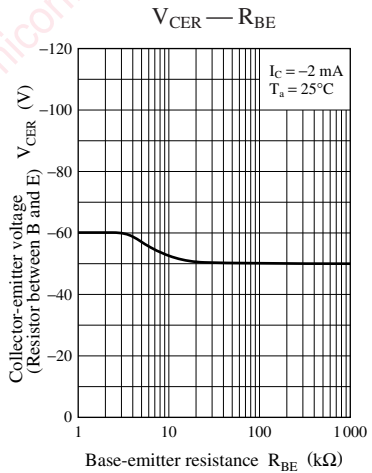
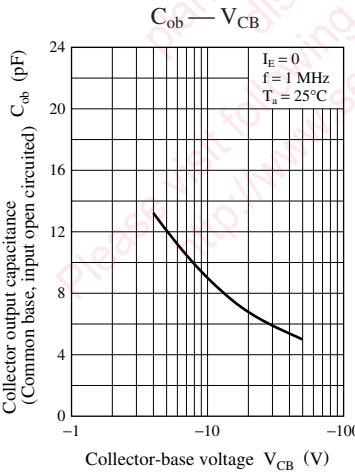
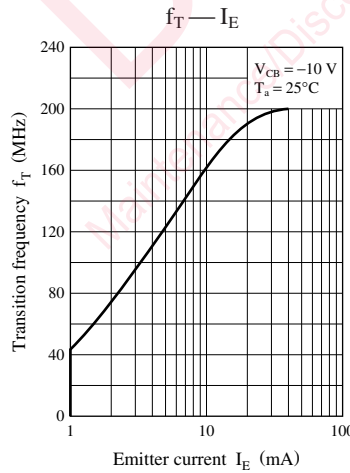
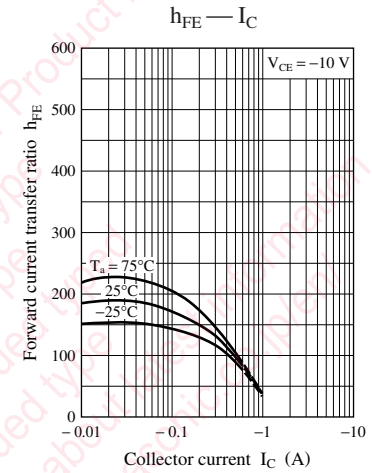
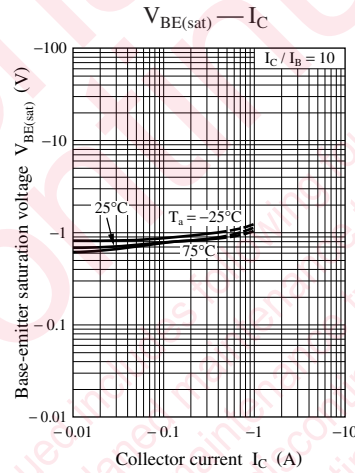
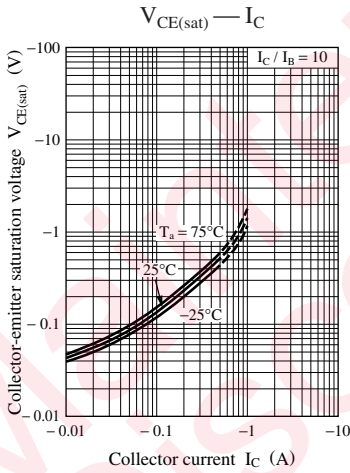
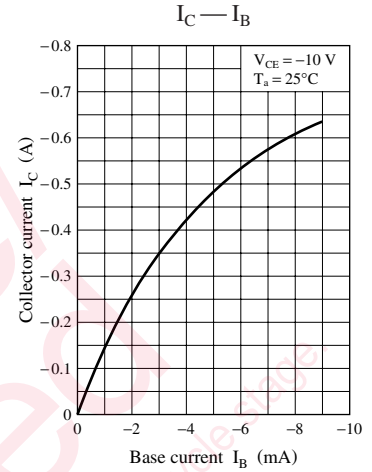
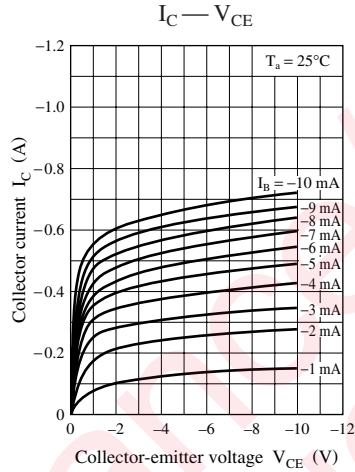
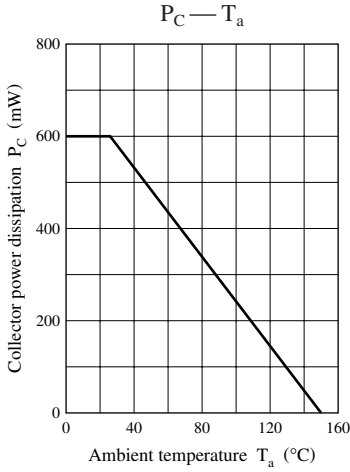
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

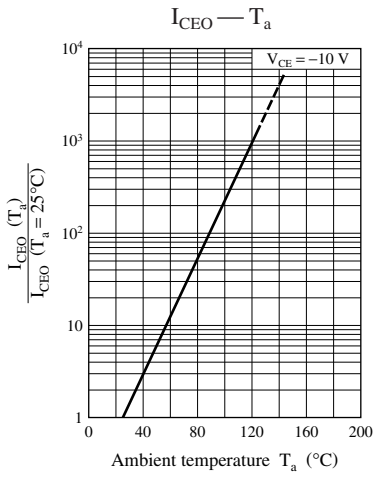
2. *1: Pulse measurement

*2: Rank classification

Rank	Q	R	S	No-rank
h_{FE1}	85 to 170	120 to 240	170 to 340	85 to 340

Product of no-rank is not classified and have no marking symbol for rank.





Maintenance/Discontinued includes following four Product lifecycle stage.
planned maintenance type
maintenance type
planned discontinued type
discontinued type
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